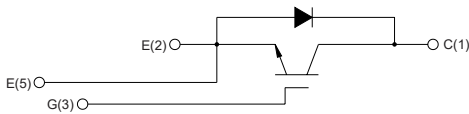


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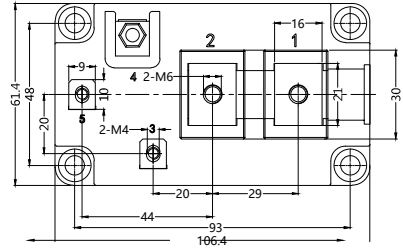
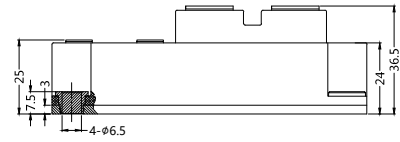
IGBT Modules



SGO800T120UC3



Dimensions in mm (1mm = 0.0394")



T_c = 25°C, unless otherwise specified

Symbol	Conditions	Values	Units
IGBT			
V _{CES}		1200	V
I _{Cnom}		800	A
I _{CRM}	T _C = 25°C, t _P =1ms	1600	A
V _{GES}		±20	V
T _{Vj}		-40...+175	°C
Inverse Diode			
I _F	T _C = 25(80)°C	920(800)	A
I _{FRM}	T _C = 25°C, t _P =1ms	1600	A
I _{FSM}	t _P =10ms; sin.; T _j =150°C	9360	A
Module			
I _{t(RMS)}	T _{terminal} = 80°C	800	A
T _{stg}		-40~125	°C
V _{Isol}	AC, 1min	4000	V

Features

- Trench Field Stop IGBT4 technology
- Low switching losses
- Switching frequency up to 20kHz
- Square RBSOA, no latch up
- High short circuit capability
- Positive temperature coefficient for easy paralleling
- MOS input, voltage controlled
- Soft switching free wheeling diode Technology
- Package with copper base plate
- Isolation voltage 4000V

Application

- AC and DC motor control
- AC servo and robot drives
- power supplies
- welding inverters

Advantages

- space and weight savings
- reduced protection circuits

SGO800T120UC3

IGBT Modules

Characteristics

T_C = 25°C, unless otherwise specified

Symbol	Conditions	min.	typ.	max.	Units
IGBT					
V _{GE(th)}	V _{GE} = V _{CE} , I _C = 8mA	5.0	5.8	6.5	V
I _{CES}	V _{GE} = 0; V _{CE} = V _{CE(sat)} ; T _j = 25(125)°C			5.0	mA
V _{CE(TO)}	T _j = 25°C		0.8	0.9	V
r _{CE}	V _{GE} = 15V, T _j = 25(150)°C		1.0(0.9)	1.2(1.1)	mΩ
V _{CE(sat)}	I _C = 800A; V _{GE} = 15V		1.90	2.15	V
C _{ies}	under following conditions		43		nF
C _{oes}	V _{GE} = 0, V _{CE} = 25V, f = 1MHz		2.25		
C _{res}			1.95		
L _{CE}			20		nH
R _{CC'+EE'}	res., terminal-chip T _C = 25(125)°C		0.18(0.22)		mΩ
t _{d(on)}	under following conditions:		220		ns
t _r	V _{CC} = 600V, I _C = 800A		100		ns
t _{d(off)}	R _{Gon} = R _{Goff} = 3Ω, T _j = 150°C		860		ns
t _f	V _{GE} = ± 15V		135		ns
E _{on} (E _{off})			65(95)		mJ
Inverse Diode under following conditions:					
V _F = V _{EC}	I _F = 800A; V _{GE} = 0V; T _j = 25(150)°C	2.20(2.15)	2.52(2.47)		V
V _(FO)	T _j = 25(150)°C	1.00(0.80)	1.10(0.90)		V
r _F	T _j = 25(150)°C	1.00(1.33)	1.17(1.50)		mΩ
I _{RRM}	I _F = 800A; T _j = 125°C		544		A
Q _{rr}	di/dt = 4450A/us		123		μC
E _{rr}	V _{GE} = 15V		59		mJ
FWD under following conditions:					
V _F = V _{EC}	I _F = 800A; V _{GE} = 0V; T _j = 25(150)°C	2.20(2.15)	2.52(2.47)		V
V _(FO)	T _j = 25(150)°C	1.00(0.80)	1.10(0.90)		V
r _F	T _j = 25(150)°C	1.00(1.33)	1.17(1.50)		mΩ
I _{RRM}	I _F = 800A; T _j = 125°C		544		A
Q _{rr}	di/dt = 4450A/us		123		μC
E _{rr}	V _{GE} = 15V		59		mJ
Thermal Characteristics					
R _{th(j-c)}	per IGBT			0.042	K/W
R _{th(j-c)D}	per Inverse Diode			0.090	K/W
R _{th(c-s)}	per module			0.038	K/W
Mechanical Data					
M _s	to heatsink M6	3		5	Nm
M _t	to terminals M6	2.5		5	Nm
Weight	typical			330	g

Sirectifier®

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IGBT Modules

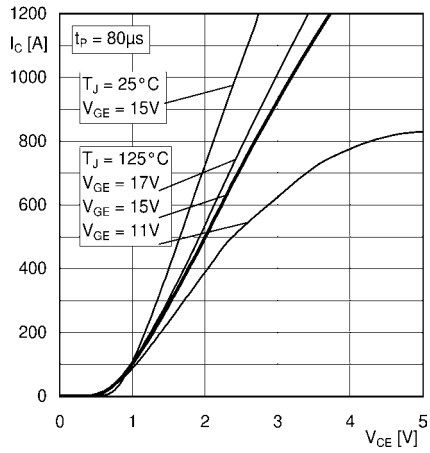


Fig. 1: Typ. output characteristic, inclusive RCC+ EE'

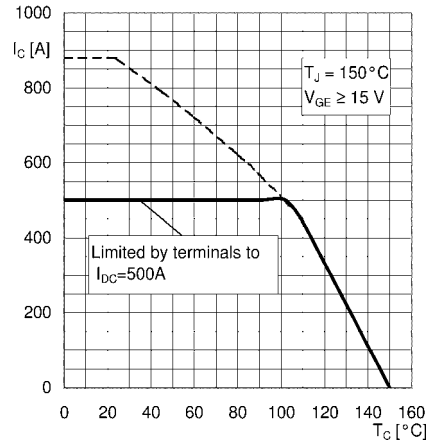


Fig. 2: Rated current vs. temperature IC = f(TC)

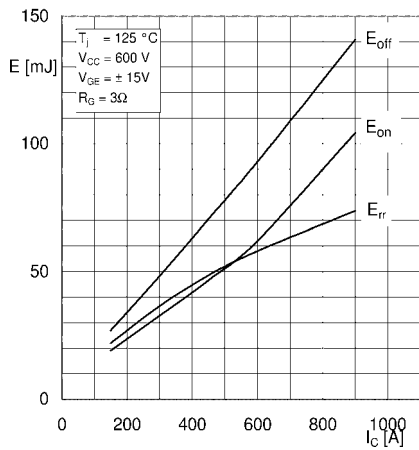


Fig. 3: Typ. turn-on /-off energy = f(IC)

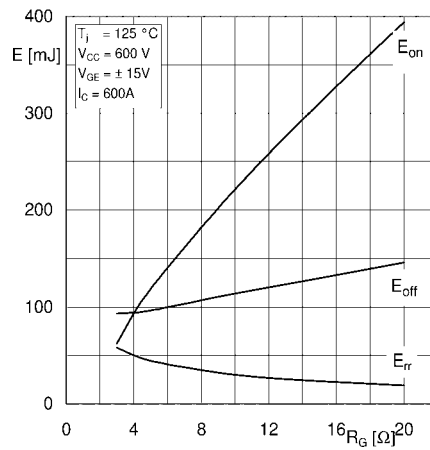


Fig. 4: Typ. turn-on /-off energy = f(RG)

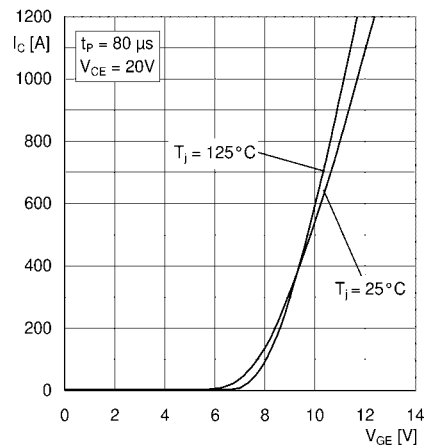


Fig. 5: Typ. transfer characteristic

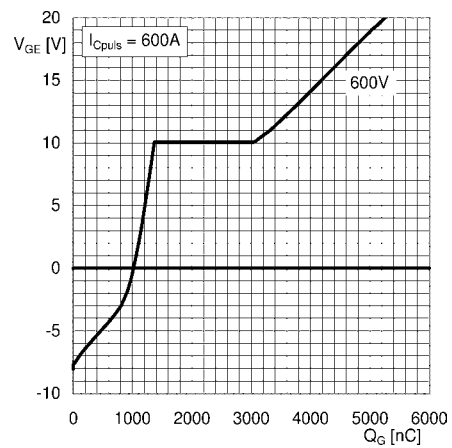


Fig. 6: Typ. gate charge characteristic

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IGBT Modules

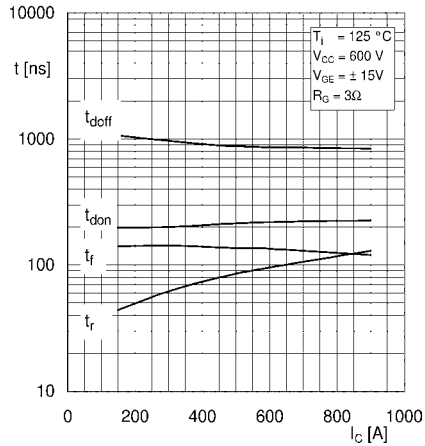


Fig. 7: Typ. switching times vs. IC

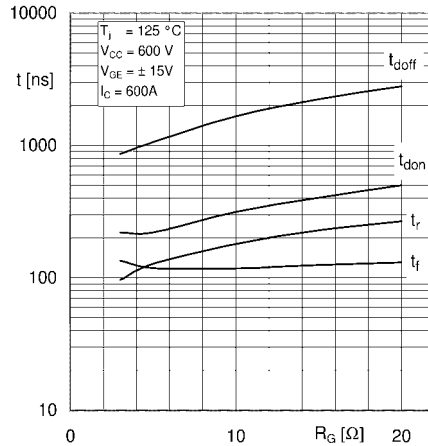


Fig. 8: Typ. switching times vs. gate resistor R_G

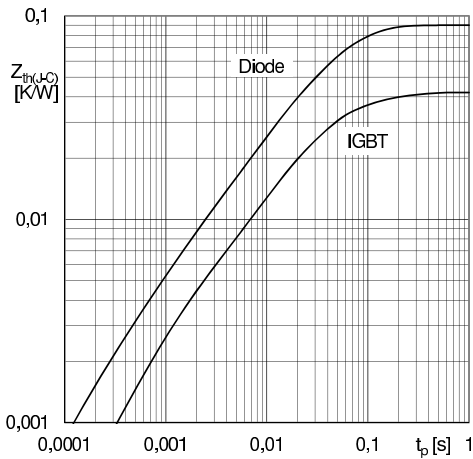


Fig. 9: Transient thermal impedance

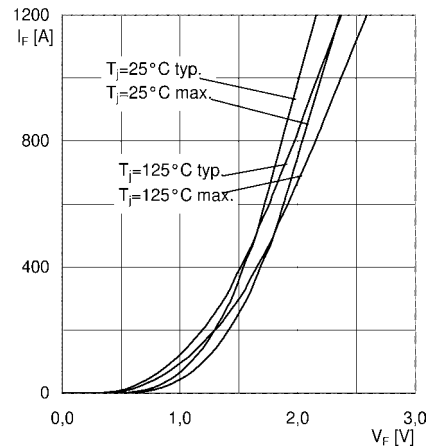


Fig. 10: Typ. CAL diode forward charact., incl. RCC'+ EE'

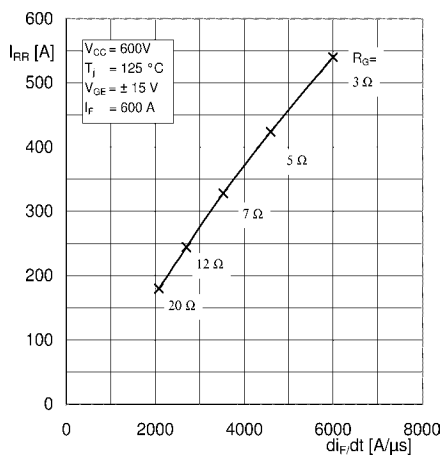


Fig. 11: Typ. CAL diode peak reverse recovery current

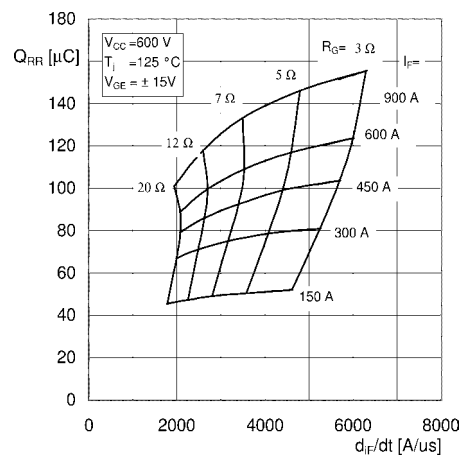


Fig. 12: Typ. CAL diode peak reverse recovery charge